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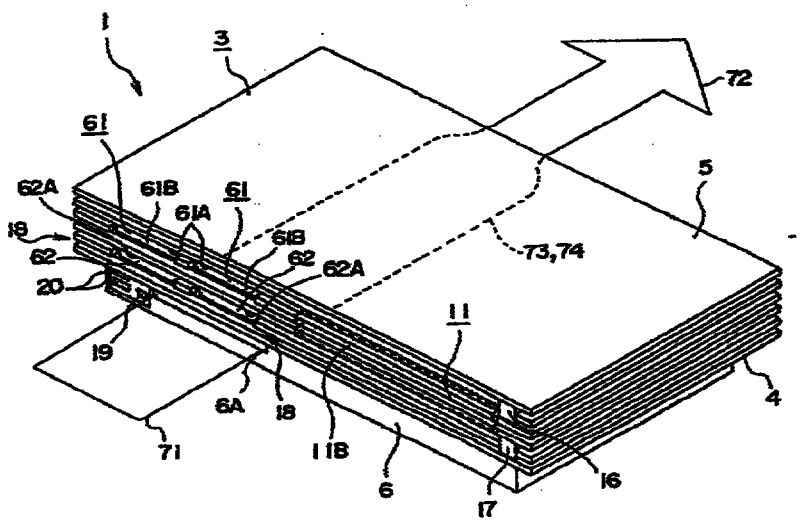
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(54) Title: ELECTRONIC DEVICE WITH HEAT GENERATING PARTS AND HEAT ABSORBING PARTS



(57) Abstract: It is an object of the present invention to provide an electronic device which realizes efficient cooling of heat-generation components and which can be downsized. According to the electronic device of the present invention, a rectangular-shaped heat sink that absorbs heat of the CPU and is placed in a cooling air intake channel (71) upstream of the power source unit. By blowing low-temperature cooling air that does not contain heat radiating from the power source unit onto the rectangular heat sink, the rectangular heat sink is cooled, and CPU heat dissipation is promoted. In this way, the CPU can be efficiently cooled so that the electronic device can be made smaller than conventional devices of the foregoing type.

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